

SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING THE SAME

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ABSTRACT OF THE DISCLOSURE

5 Semiconductor packages having a thin structure capable
of easily discharging heat from a semiconductor chip
included therein, and methods for fabricating such
semiconductor packages, are disclosed. An embodiment of a
semiconductor package includes a semiconductor chip having a
10 first major surface and a second major surface, the
semiconductor chip being provided at the second major
surface with a plurality of input/output pads; a circuit
board including a resin substrate having a first major
surface and a second major surface, a first circuit pattern
15 formed at the first major surface and provided with a
plurality of ball lands, a second circuit pattern formed at
the second major surface and provided with a plurality of
bond fingers connected with the ball lands by conductive via
holes through the resin substrate, cover coats respectively
20 coating the first and second circuit patterns while allowing
the bond fingers and the ball lands to be exposed
therethrough, and a central through hole adapted to receive
the semiconductor chip therein; electrical conductors that
electrically connect the input/output pads of the
25 semiconductor chip with the bond fingers of the circuit
board, respectively; a resin encapsulate that covers the
semiconductor chip, the electrical conductors, and at least
part of the circuit board; and, a plurality of conductive
balls fused on the ball lands of the circuit board,
30 respectively.